



PMEG100T20ELR-Q

100 V, 2 A low leakage current Trench MEGA Schottky barrier rectifier

12 July 2021

Product data sheet

1. General description

Trench Maximum Efficiency General Application (MEGA) Schottky barrier rectifier encapsulated in a CFP3 (SOD123W) small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Low forward voltage
- Low Q_{rr} and low I_{RM}
- Low leakage current
- High power capability due to clip-bonding technology
- Small and flat lead SMD power plastic package
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- High efficiency DC-to-DC conversion
- Automotive LED lighting
- Switch mode power supply
- Freewheeling applications
- Reverse polarity protection
- OR-ing

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20$ kHz; square wave; $T_{sp} \leq 156$ °C		-	-	2	A
V_R	reverse voltage	$T_j = 25$ °C		-	-	100	V
V_F	forward voltage	$I_F = 2$ A; pulsed; $T_j = 25$ °C	[1]	-	705	800	mV
I_R	reverse current	$V_R = 100$ V; pulsed; $T_j = 25$ °C	[1]	-	0.15	1.25	µA
		$V_R = 100$ V; pulsed; $T_j = 125$ °C	[1]	-	0.28	1.2	mA

[1] Very short pulse, in order to maintain a stable junction temperature.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 CFP3 (SOD123W)	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG100T20ELR-Q	CFP3	plastic, surface mounted package; 2 terminals; 2.6 mm x 1.7 mm x 1 mm body	SOD123W

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG100T20ELR-Q	LB

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	$T_j = 25\text{ }^{\circ}\text{C}$		-	100	V
I_F	forward current	$\delta = 1$; $T_{sp} \leq 150\text{ }^{\circ}\text{C}$		-	2.8	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{sp} \leq 156\text{ }^{\circ}\text{C}$		-	2	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8.3\text{ ms}$; half sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$		-	50	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ }^{\circ}\text{C}$	[1]	-	0.68	W
			[2]	-	1.15	W
T_j	junction temperature			-	175	$^{\circ}\text{C}$
T_{amb}	ambient temperature			-55	175	$^{\circ}\text{C}$
T_{stg}	storage temperature			-65	175	$^{\circ}\text{C}$

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	220	K/W
			[1] [3]	-	-	130	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	18	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.

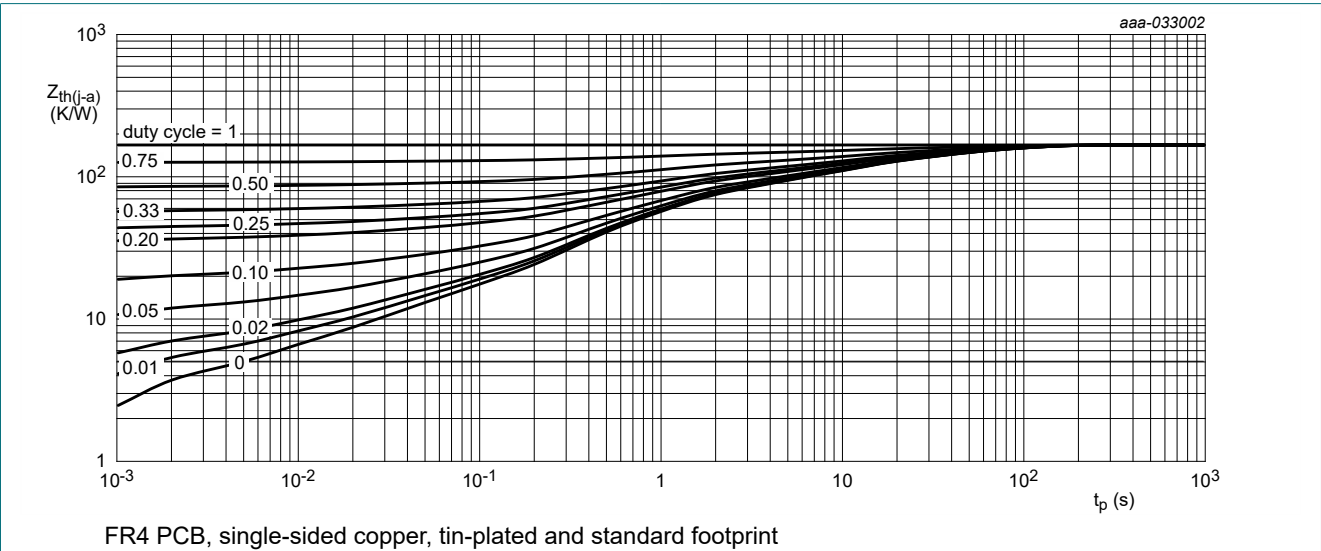


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

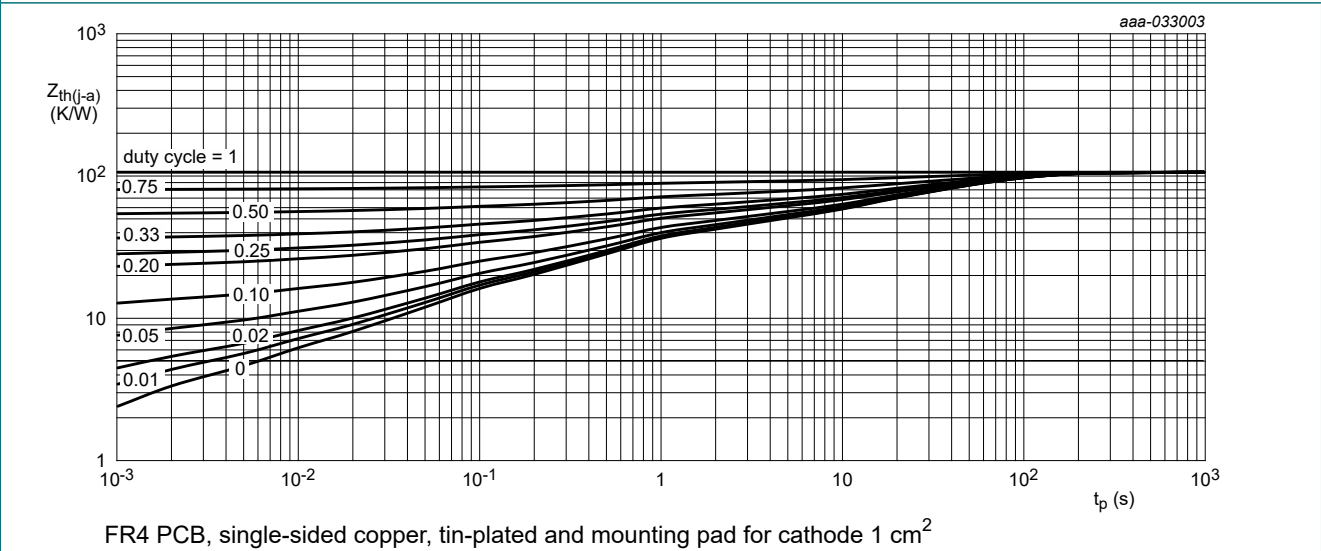


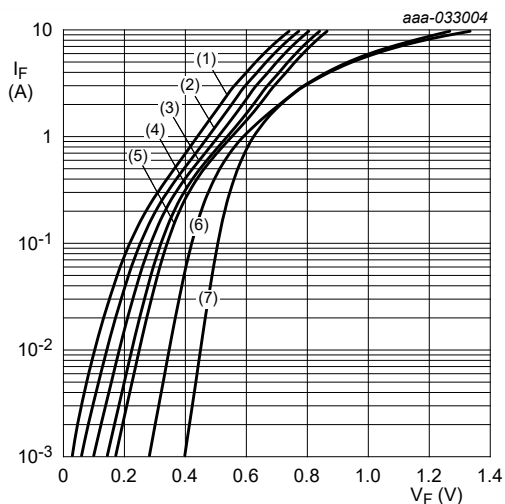
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 1 \text{ mA}$; $T_j = 25 \text{ }^\circ\text{C}$	[1]	100	-	-	V
V_F	forward voltage	$I_F = 0.1 \text{ A}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	420	490	mV
		$I_F = 0.5 \text{ A}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	515	580	mV
		$I_F = 1 \text{ A}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	590	660	mV
		$I_F = 2 \text{ A}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	705	800	mV
		$I_F = 2 \text{ A}$; pulsed; $T_j = -40 \text{ }^\circ\text{C}$	[1]	-	705	800	mV
		$I_F = 2 \text{ A}$; pulsed; $T_j = 125 \text{ }^\circ\text{C}$	[1]	-	590	660	mV
		$I_F = 2 \text{ A}$; pulsed; $T_j = 150 \text{ }^\circ\text{C}$	[1]	-	550	620	mV
I_R	reverse current	$V_R = 60 \text{ V}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	0.06	0.5	μA
		$V_R = 100 \text{ V}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	0.15	1.25	μA
		$V_R = 100 \text{ V}$; pulsed; $T_j = 125 \text{ }^\circ\text{C}$	[1]	-	0.28	1.2	mA
		$V_R = 100 \text{ V}$; pulsed; $T_j = 150 \text{ }^\circ\text{C}$	[1]	-	1.1	5.5	mA
C_d	diode capacitance	$V_R = 1 \text{ V}$; $f = 1 \text{ MHz}$; $T_j = 25 \text{ }^\circ\text{C}$		-	200	-	pF
		$V_R = 10 \text{ V}$; $f = 1 \text{ MHz}$; $T_j = 25 \text{ }^\circ\text{C}$		-	60	-	pF
t_{rr}	reverse recovery time step recovery	$I_F = 0.5 \text{ A}$; $I_R = 0.5 \text{ A}$; $I_{R(\text{meas})} = 0.1 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$		-	6	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 200 \text{ A}/\mu\text{s}$; $I_F = 6 \text{ A}$; $V_R = 26 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$		-	12	-	ns
I_{RM}	peak reverse recovery current	$dI_F/dt = 200 \text{ A}/\text{s}$; $I_F = 6 \text{ A}$; $V_R = 26 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$		-	1.3	-	A
Q_{rr}	reverse recovery charge			-	8.5	-	nC
V_{FRM}	peak forward recovery voltage	$I_F = 0.5 \text{ A}$; $dI_F/dt = 20 \text{ A}/\mu\text{s}$; $T_j = 25 \text{ }^\circ\text{C}$		-	520	-	mV

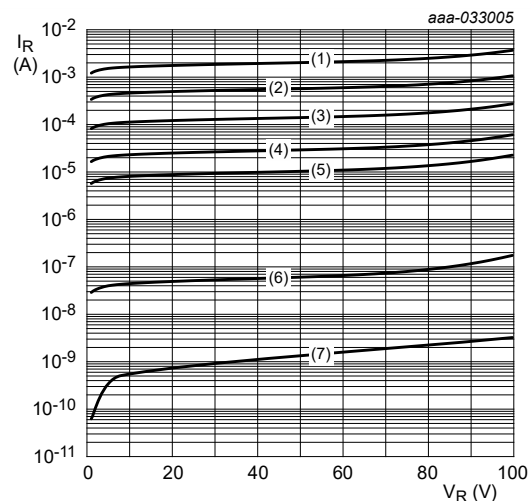
[1] Very short pulse, in order to maintain a stable junction temperature.



pulsed condition

- (1) $T_j = 175\text{ }^{\circ}\text{C}$
- (2) $T_j = 150\text{ }^{\circ}\text{C}$
- (3) $T_j = 125\text{ }^{\circ}\text{C}$
- (4) $T_j = 100\text{ }^{\circ}\text{C}$
- (5) $T_j = 85\text{ }^{\circ}\text{C}$
- (6) $T_j = 25\text{ }^{\circ}\text{C}$
- (7) $T_j = -40\text{ }^{\circ}\text{C}$

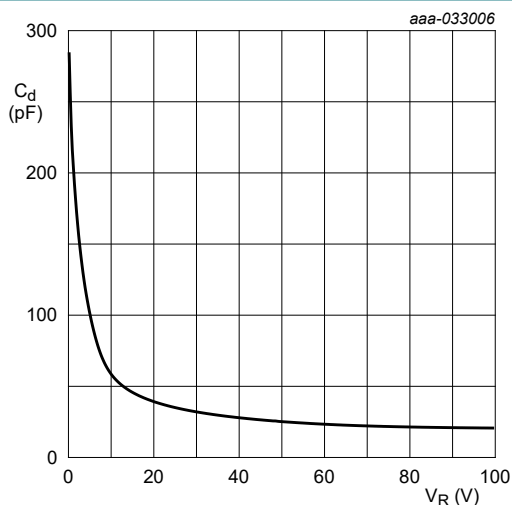
Fig. 3. Forward current as a function of forward voltage; typical values



pulsed condition

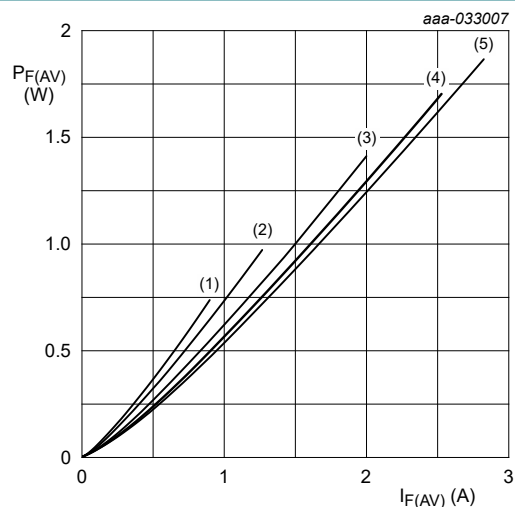
- (1) $T_j = 175\text{ }^{\circ}\text{C}$
- (2) $T_j = 150\text{ }^{\circ}\text{C}$
- (3) $T_j = 125\text{ }^{\circ}\text{C}$
- (4) $T_j = 100\text{ }^{\circ}\text{C}$
- (5) $T_j = 85\text{ }^{\circ}\text{C}$
- (6) $T_j = 25\text{ }^{\circ}\text{C}$
- (7) $T_j = -40\text{ }^{\circ}\text{C}$

Fig. 4. Reverse current as a function of reverse voltage; typical values



$f = 1\text{ MHz}$; $T_{\text{amb}} = 25\text{ }^{\circ}\text{C}$

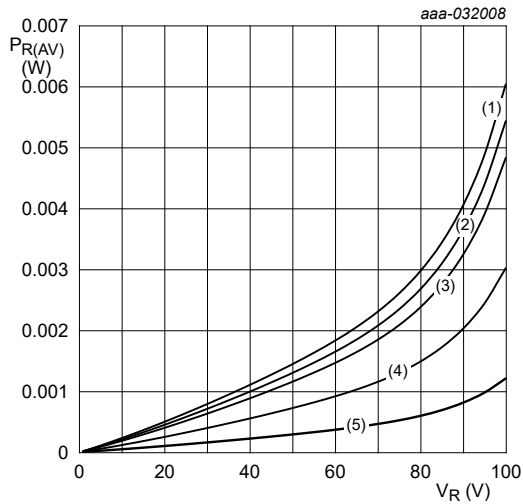
Fig. 5. Diode capacitance as a function of reverse voltage; typical values



$T_j = 100\text{ }^{\circ}\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 0.8$
- (5) $\delta = 1$; DC

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



$T_j = 100\text{ }^{\circ}\text{C}$

(1) $\delta = 1$; DC

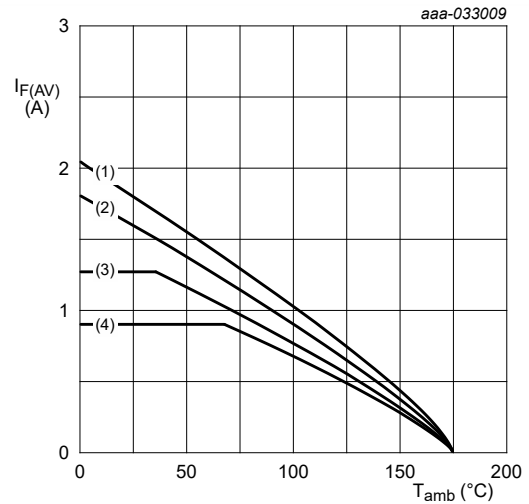
(2) $\delta = 0.9$

(3) $\delta = 0.8$

(4) $\delta = 0.5$

(5) $\delta = 0.2$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

$T_j = 175\text{ }^{\circ}\text{C}$

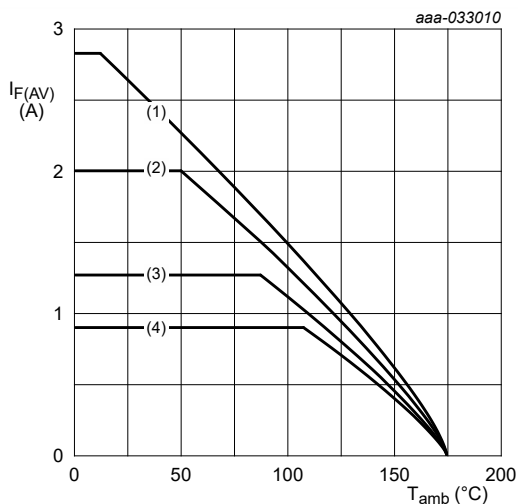
(1) $\delta = 1$; DC

(2) $\delta = 0.5$; $f = 20\text{ kHz}$

(3) $\delta = 0.2$; $f = 20\text{ kHz}$

(4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm^2

$T_j = 175\text{ }^{\circ}\text{C}$

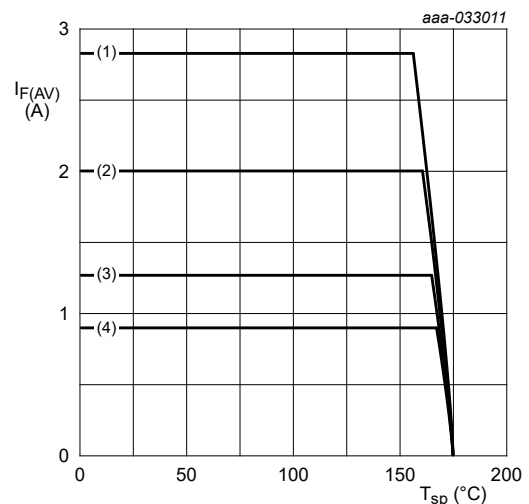
(1) $\delta = 1$; DC

(2) $\delta = 0.5$; $f = 20\text{ kHz}$

(3) $\delta = 0.2$; $f = 20\text{ kHz}$

(4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 9. Average forward current as a function of ambient temperature; typical values



$T_j = 175\text{ }^{\circ}\text{C}$

(1) $\delta = 1$; DC

(2) $\delta = 0.5$; $f = 20\text{ kHz}$

(3) $\delta = 0.2$; $f = 20\text{ kHz}$

(4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 10. Average forward current as a function of solder point temperature; typical values

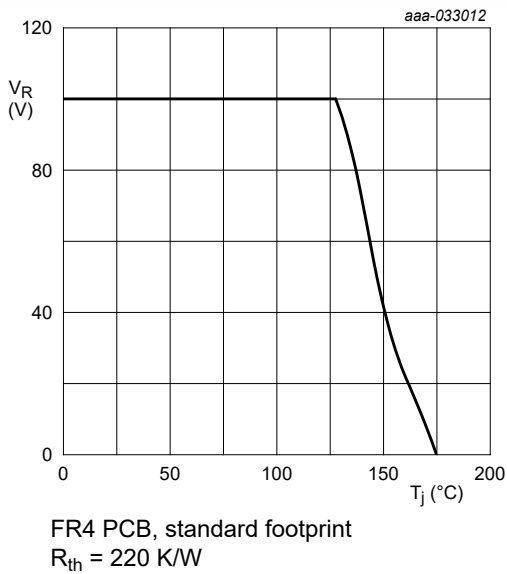


Fig. 11. Derated maximum reverse voltage as a function of junction temperature; typical values

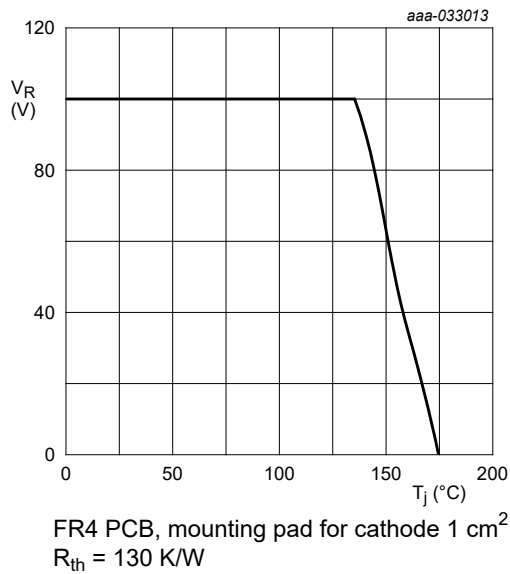


Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values

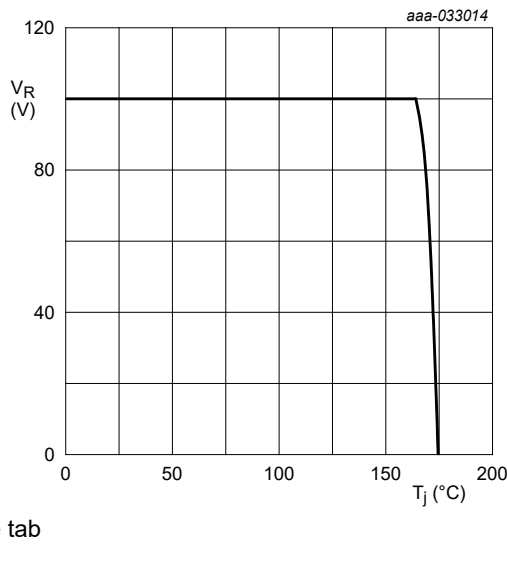


Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

11. Test information

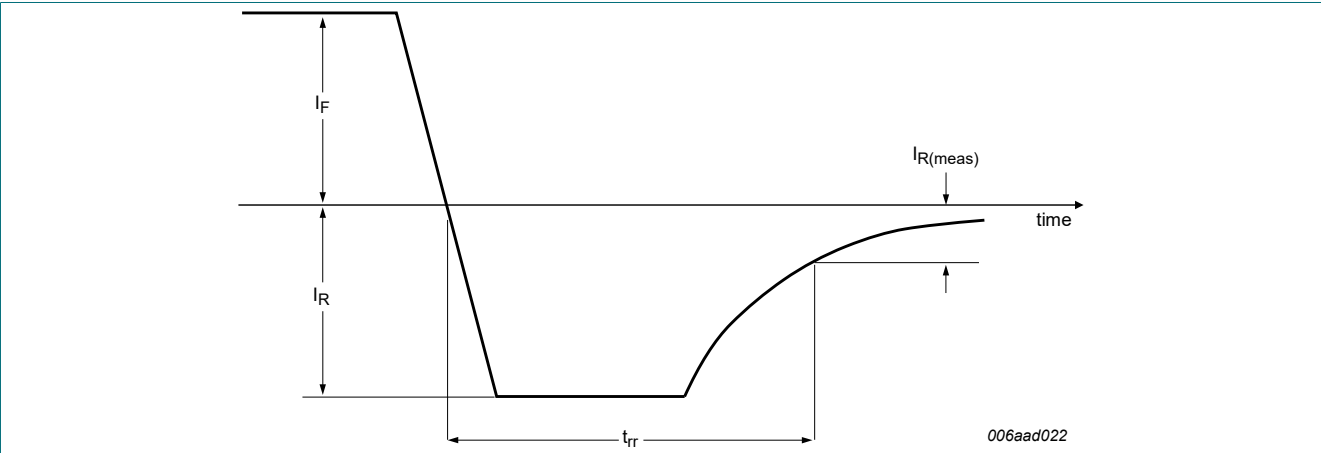


Fig. 14. Reverse recovery definition; step recovery

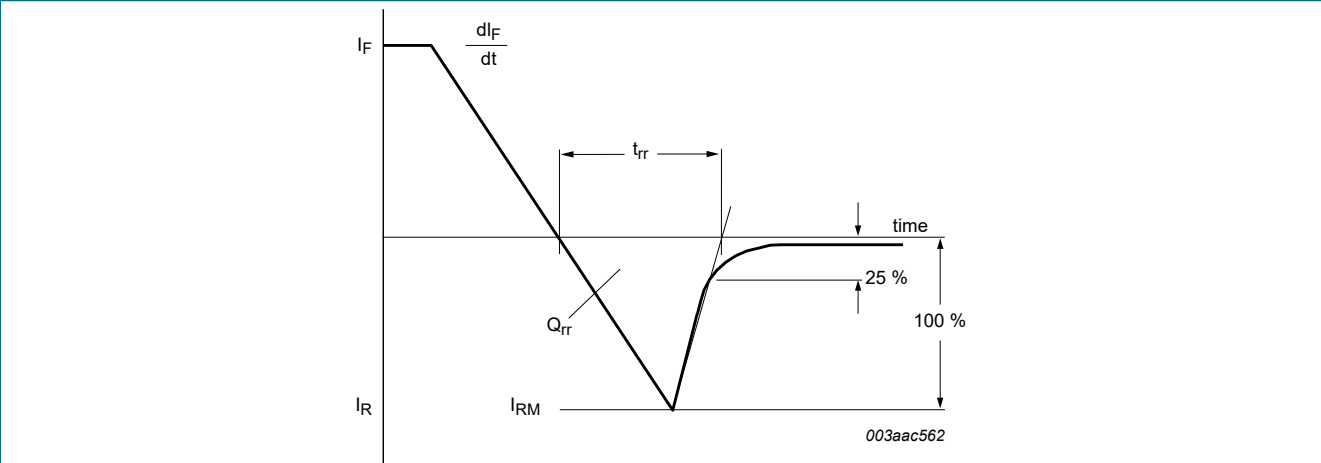


Fig. 15. Reverse recovery definition; ramp recovery

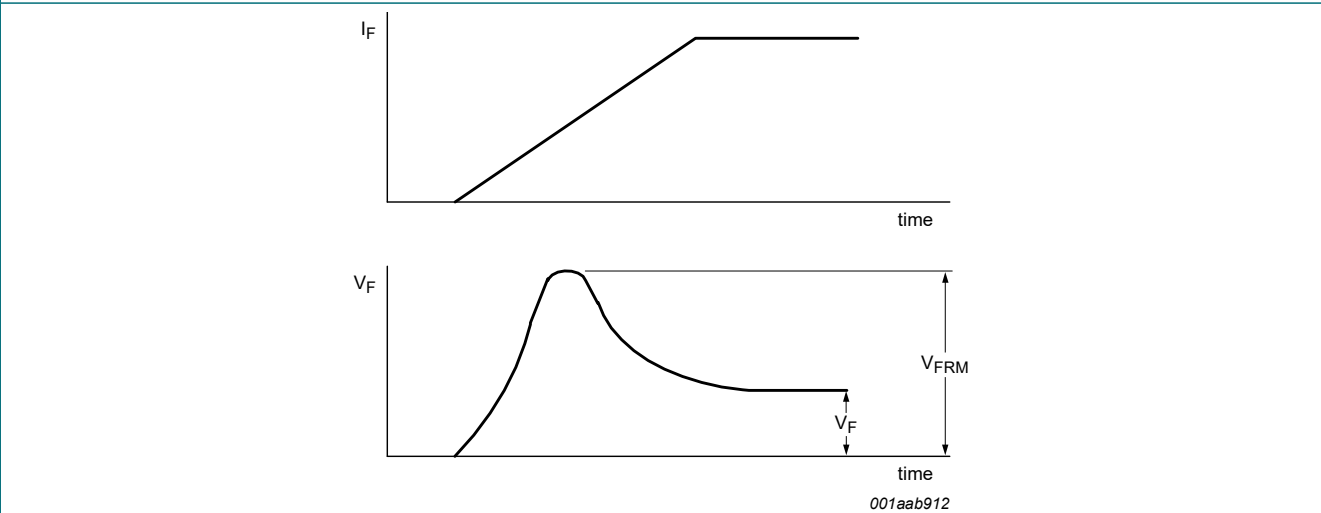


Fig. 16. Forward recovery definition

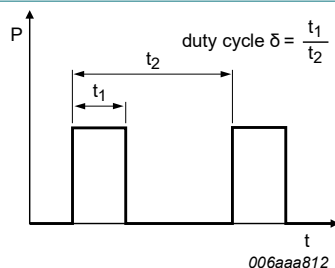


Fig. 17. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC, and } I_{RMS} = I_M \times \sqrt{\delta}$$

with I_{RMS} defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

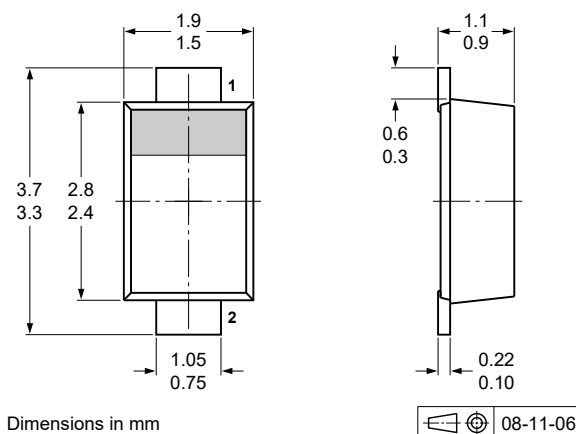
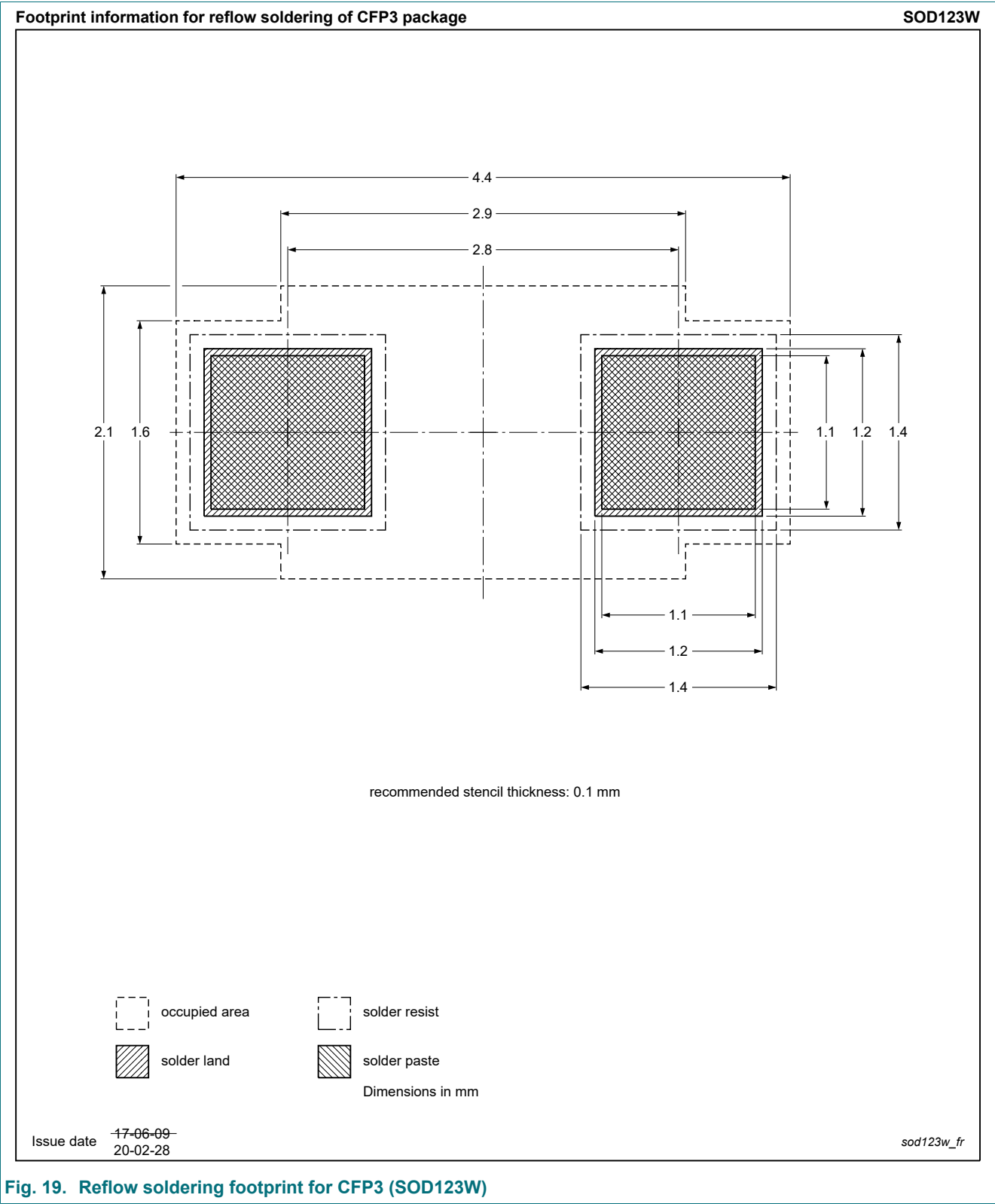


Fig. 18. Package outline CFP3 (SOD123W)

13. Soldering



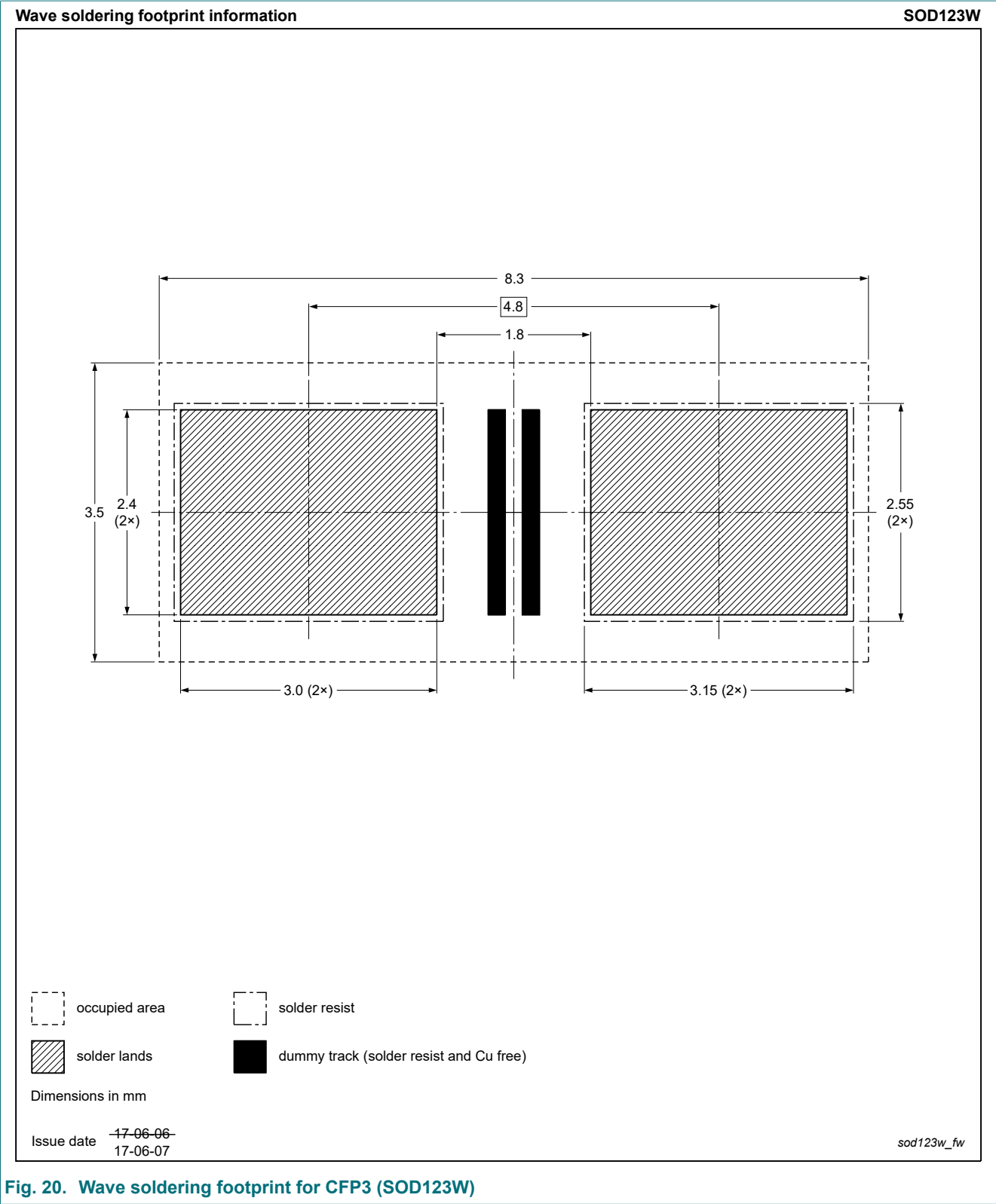


Fig. 20. Wave soldering footprint for CFP3 (SOD123W)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG100T20ELR-Q v.2	20210712	Product data sheet	-	PMEG100T20ELR-Q v.1
Modifications:	• Figure 6 adapted			
PMEG100T20ELR-Q v.1	20210519	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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